

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application.

- 1) (currently amended) A rigid-flex printed circuit board system comprising, in combination:
  - a) at least one rigid layer;
  - b) wherein said at least one rigid layer comprises
    - i) at least one top side, and
    - ii) at least one bottom side;
  - c) at least one first flexible layer bonded to at least one first portion of said at least one top side;
  - d) at least one second flexible layer bonded to at least one second portion of said at least one bottom side;
  - e) wherein said at least one rigid layer comprises at least one first structural weakness at at least one first selected location;
  - f) wherein said at least one first structural weakness is structured and arranged to facilitate breaking said at least one rigid layer at such at least one first selected location into at least two rigid pieces to provide a at least one first flexible connection formed by said at least one first flexible layer between such rigid pieces;
  - g) wherein said at least one rigid layer comprises at least one second structural weakness at at least one second selected location; and
  - h) wherein said at least one second structural weakness is adapted to



facilitate breaking said at least one rigid layer at such at least one second  
selected location into at least two second rigid pieces to provide at least  
one second flexible connection formed by said at least one second flexible  
layer between such second rigid pieces.

- 2) (previously presented) The rigid-flex printed circuit board system according to Claim 1 wherein such first structural weakness comprises at least one score that partially penetrates said at least one rigid layer.
- 3) (previously presented) The rigid-flex printed circuit board system according to Claim 1 wherein:
  - a) said structural weakness comprises
    - i) at least one top score on said at least one top side at such at least one first selected location, and
    - ii) at least one bottom score on said at least one bottom side at such at least one first elected location.
- 4) (canceled)
- 5) (previously presented) The rigid-flex printed circuit board system according to Claim 1 further comprising:
  - a) at least one adhesive to bond at least one flexible layer portion of said at least one first flexible layer to at least one rigid layer portion of said at least one rigid layer;
  - b) wherein said structural weakness comprises selective absence of adhesive at such selected location between said at least one rigid layer and said at least one flexible layer.



- 6) (previously presented) The rigid-flex printed circuit board system according to Claim 1 wherein said at least one first structural weakness comprises at least one laser score.
- 7) (previously presented) The rigid-flex printed circuit board system according to Claim 1 wherein said at least one first structural weakness comprises at least one mechanical score.
- 8) (canceled)
- 9) (canceled)
- 10) (original) The rigid-flex printed circuit board system according to Claim 1 wherein said at least one rigid layer comprises fiberglass.
- 11) (previously presented) The rigid-flex printed circuit board system according to Claim 1 wherein said at least one first flexible layer comprises polyimide.
- 12) (previously presented) The rigid-flex printed circuit board system according to Claim 1 wherein:
  - a) said at least one first flexible layer comprises
    - i) at least one substantially flexible insulating layer, and
    - ii) at least one substantially flexible conductive layer; and
  - b) said at least one rigid layer comprises
    - i) at least one substantially rigid insulating layer, and
    - ii) at least one conductive layer.
- 13-15) (canceled)
- 16) (currently amended) The rigid-flex printed circuit board system according to Claim ~~13~~1 wherein said at least one first structural weakness comprises at least one groove.



- 17) (currently amended) The rigid-flex printed circuit board system according to Claim ~~13~~1 wherein said at least one first structural weakness comprises at least one chemically milled groove.
- 18-41) (canceled)
- 42) (previously presented) The rigid-flex printed circuit board system according to Claim 1 wherein
- a) said at least one first flexible layer comprises at least one top outermost layer; and
  - b) said at least one second flexible layer comprises at least one bottom outermost layer.
- 43) (previously presented) The rigid-flex printed circuit board system according to Claim 1 further comprising at least one breakaway portion.
- 44) (canceled)
- 45) (currently amended) The rigid-flex printed circuit board system according to Claim ~~44~~1 wherein
- a) said at least one first flexible connection is structured and arranged to provide upwardly concave flexure at said at least one first selected location; and
  - b) said at least one second flexible connection is structured and arranged to provide downwardly concave flexure at said at least one second selected location.
- 46) (previously presented) The rigid-flex printed circuit board system according to Claim 2 wherein said at least one score penetrates about two-thirds of the total thickness of said at least one rigid layer.
- 47-50) (canceled)